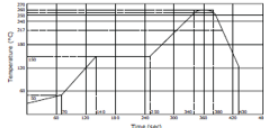


PREVIOUS CUI DEVICE'S DETAIL / IMAGE **NEW CUI DEVICE'S DETAIL / IMAGE**

SOLDERABILITY

parameter	conditions/description	min	typ	max	units
reel storage	at relative humidity <80%			40	°C
reflow soldering ¹	see reflow profile	255	260	265	°C
drying conditions ²	parts in reel: bake at 40°C ±5°C for 72 hours parts removed from reel: bake at 40°C ±5°C for 10 hours				

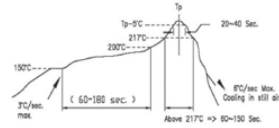
Note: 1. It is recommended to reflow solder within 72 hours from opening vacuum packaging at a temperature >30°C & relative humidity <60%.
2. When exceeding 90% by >72 hours.



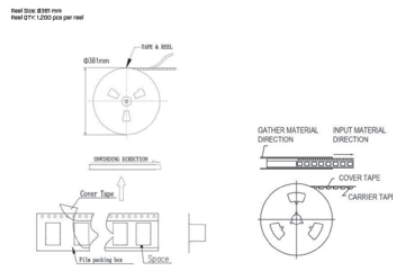
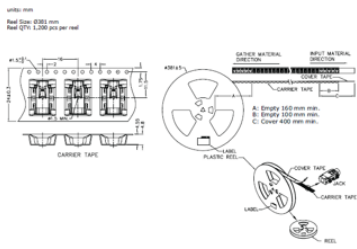
SOLDERABILITY

parameter	conditions/description	min	typ	max	units
reel storage ¹	10-30°C, <70% humidity				°C
reflow soldering ²	see reflow profile	255	260		°C
drying conditions ²	parts in reel: bake at 110°C for 4 hours parts removed from reel: bake at 110°C for 4 hours				

Note: 1. CUI Devices recommends to solder within 72 hours from opening vacuum packaging at a temperature >30°C & relative humidity <60%.
2. When exceeding 90% by >72 hours.



* Time 25°C to Peak Temp. --- 8 Minutes Max.
* Time within 5°C of Actual Peak Temp. --- 20-40 Seconds




Affected Date Code: **07/10/2023**

Product Availability: *Pertaining to market availability*

PCN Approval:

Operations/Quality



Product Management

